



Lead-free, halogen free, no-clean solder wire

Description:

Interflux[®] **Quick Flow QF 70** solder wire for lead-free alloys is an absolutely halogen free no-clean solder wire that has been designed to give fast wetting.

QF 70 solder wire contains absolutely no halogens and is classified as RO L0 according to IPC and EN-standards.

The solder wire has increased wetting speed, compared to conventional halogen free solder wires.

QF 70 has low spattering properties.

The solder wire can be used in both hand soldering and automated soldering processes.

The residue after soldering is transparent.



Products pictured may differ from the product delivered



Key properties

- Increased wetting speed
- Low spattering
- Transparent residue
- Absolutely halogen free
- Suitable for automated soldering

Availability

Flux type: QF 70
Flux content: 2,2 % and 3% w/w

alloy	melting point	diameters						
		0,35	0,50	0,70	1,00	1,50	2,00	
Sn96,5Ag3,0Cu0,5	+/-217°C	●	●	●	●	●	●	
Sn95,5Ag3,8Cu0,7	+/-217°C	●	●	●	●	●	●	
Sn99Ag0,3Cu0,7	+/-217°C—227°C	●	●	●	●	●	●	
Sn99,3Cu0,7	+/-227°C	●	●	●	●	●	●	
Other alloys upon request		Other diameters upon request						

● = available

● = upon request





Work Instructions

Manual soldering

The advised working temperature is between 320°C and 390°C. For more dense metals like Nickel, the temperature may be elevated to 420°C.

The use of a good soldering station is important. Use a soldering station with a short response time and with enough power for your application.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact area with the surfaces to be soldered.

Heat up both the surfaces simultaneously. Slightly touch with the solder wire, the point where soldering tip and the surfaces to be soldered meet (the small quantity of solder ensures a drastic lowering

of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip.

This will reduce the risk on premature flux consumption!

The regular use of a non abrasive tip tinner like Interflux[®] TIP TINNER followed by a wipe on a

damp sponge can prolong tip life substantially and will avoid dark spots in the residue.

Handling

Storage

Store the solder wire in a clean environment at ambient temperature.

Handling

To avoid spool and wire damage, handle package with care.

Safety

Please always consult the safety datasheet of the product.

Test results

Conform EN 61190-1-3(2007) and IPC J-STD-004(A)

Property	Result	Method
Chemical		
flux designator	RO L0	J-STD-004A
% halide content	0,00%	
qualitative copper mirror	pass	J-STD-004 IPC-TM-650 2.3.32D
silver chromate (Cl, Br)	pass	J-STD-004 IPC-TM-650 2.3.33D
spot test (F)	pass	J-STD-004 IPC-TM-650 2.3.35.1
Environmental		
SIR test	pass	J-STD-004 IPC-TM-650 2.6.3.3B
qualitative corrosion, flux	pass	J-STD-004 IPC-TM-650 2.6.15
Other		
spread test	102,21 mm²	J-STD-004 IPC-TM-650 2.4.46
dryness test	pass	J-STD-004 IPC-TM-650 2.6.47



Packaging

Spools of 100g, 500g and 1000g

Not all diameters are available on all spool sizes

Trade name: Quick Flow QF 70 Lead-free, No-Clean Solder Wire

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